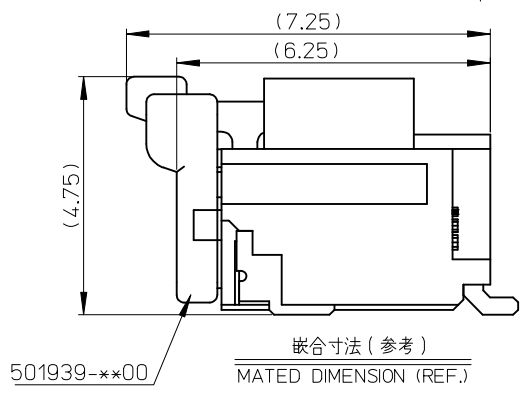
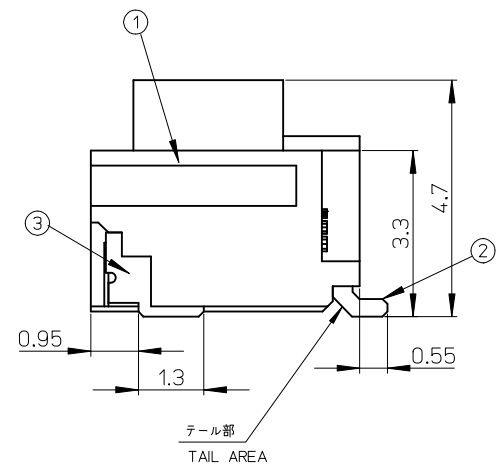
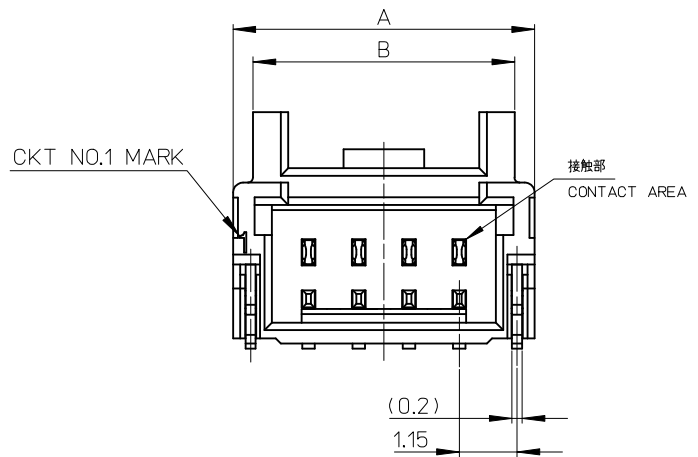


参考パターンレイアウト
RECOMMENDED PATTERN DIM. (REF)
SCALE 5:1



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON .COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ (接触部):0.1μm MIN. GOLD PLATING (CONTACT AREA) 金メッキ (テール部):0.05μm MIN. GOLD PLATING (TAIL AREA) ニッケルメッキ (下地):1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ:1.0μmMIN. TIN ニッケルメッキ (下地):1.0μmMIN. NICKEL(UNDER PLATING)

NOTES.

1. 嵌合相手: 501939-****
MATE WITH: 501939-****
2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
3. 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. ELV AND RoHS COMPLIANT.


4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

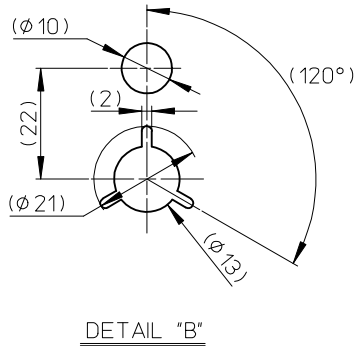
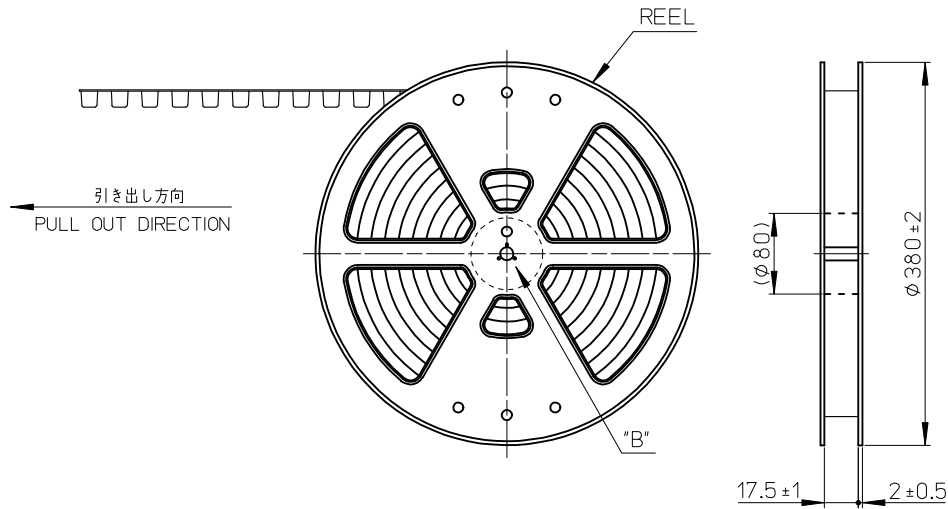
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REVISED EC NO: J2016-1063 DR:WNR/TAKAKAOZ 2016/04/07 CHKD:SAKI/YAMA 2016/04/08 APPR:TKANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		CONNECTOR SERIES No. 501953-***6		
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	10:1	METRIC	
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	TITLE		
1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE				
30 OVER		±0.3	NUKITA	2015/01/16				
ANGULAR	±3 °		MATERIAL NO.		DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	SEE SHEET 2		SD-501953-003		SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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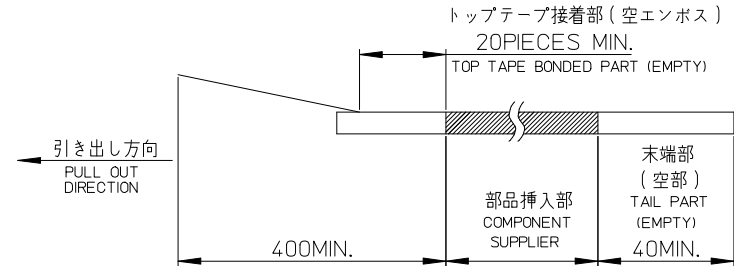
紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	5
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	4
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	3
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES No. 501953-***9				
青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL 色 COLOR
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	501953-0505 5
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	501953-0405 4
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	501953-0305 3
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES No. 501953-***6				

REVISED EC NO: J2016-1063 DRWR: TANKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25			
	10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
ANGULAR	±3 °		SEE CHART		SD-501953-003		2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



NOTES

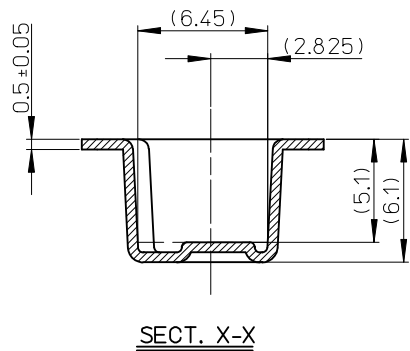
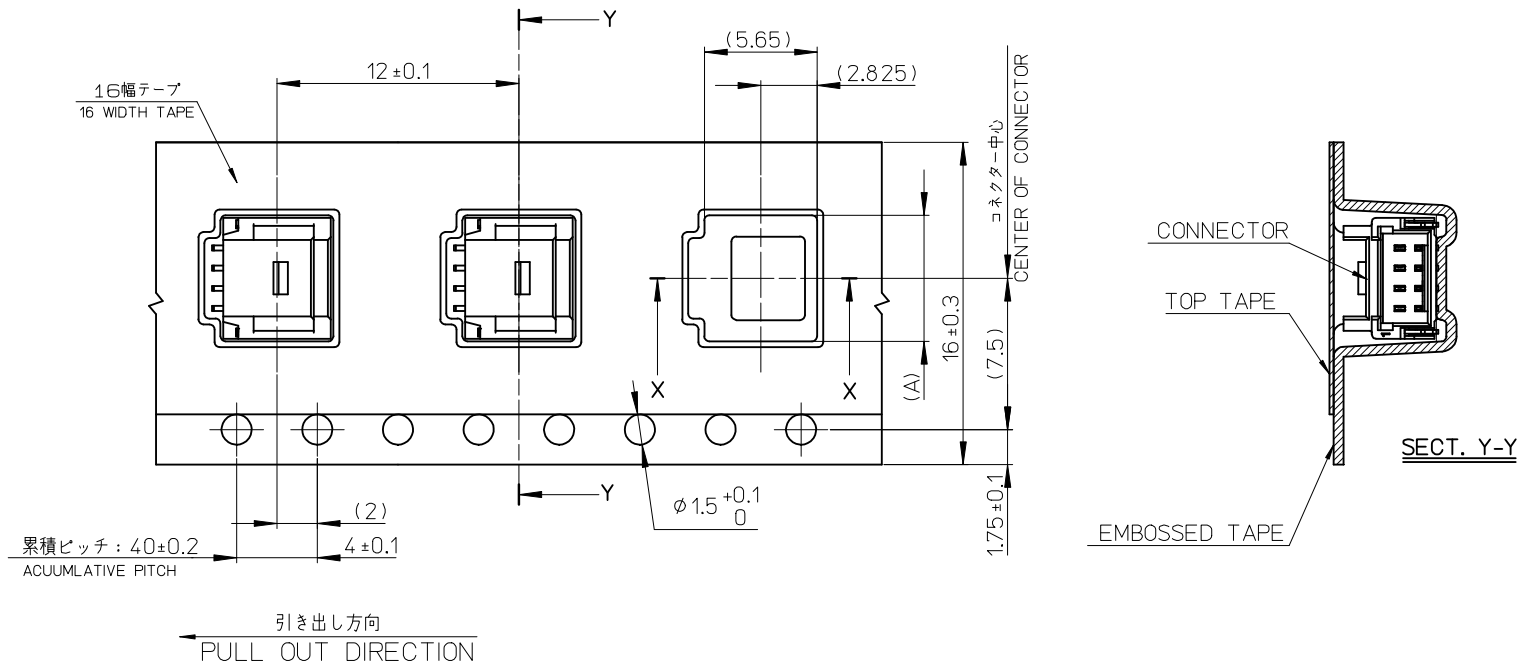
- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1300個/リール
NUMBER OF CONNECTORS: 1300PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ: ポリスチレン
CARRIER TAPE: POLYSTYRENE
トップテープ: PET、その他
TOP TAPE: PET, OTHER
リール: ポリスチレン<リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
- ELV AND RoHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501953-**07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501953-**07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501940-001参照)
REFER TO PS-501940-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2016-1063 DRWR: TANAKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	± 0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
	0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	± 0.2	KASAKAWA	2014/12/25			
	10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE			
30 OVER		± 0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
ANGULAR	± 3 °		SEE SHEET 3		SD-501953-004	1 OF 3		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-***6

REVISED EC NO: J2016-1063 DRWR: TANKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	± 0.03	DRAWN BY KCHIKANO	DATE 2014/12/25	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY KASAKAWA	DATE 2014/12/25			
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY NUKITA	DATE 2015/01/16			
	1.0 OVER	30 UNDER	± 0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
10 OVER	30 UNDER	± 0.25	SEE SHEET 3		SD-501953-004		2 OF 3	
30 OVER		± 0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR		± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

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	紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
					5
					4
					3
	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 501953-***9					
	青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL
					501953-0505
					501953-0405
					501953-0305
	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

REVISED EC NO: J2016-1063 DRWR: TANKA02 CHKD: SAKIYAMA APPR: KANEKO	2016/04/07 2016/04/08 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
		0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
		1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE					
30 OVER		±0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
ANGULAR ±3 °			SEE CHART		SD-501953-004		3 OF 3		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				